TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $L^2$ - $\pi$ -MOSVI)

# 2SK2964

# Chopper Regulators, DC-DC Converters and Motor DriveApplications

• 4-V gate drive

• Low drain-source ON-resistance: RDS (ON) =  $0.13 \Omega$  (typ.)

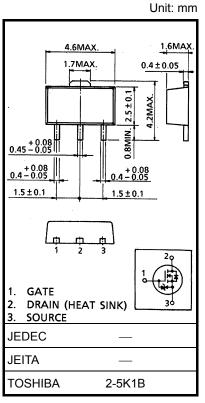
• High forward transfer admittance:  $|Y_{fs}| = 2.5 \text{ S (typ.)}$ 

• Low leakage current: IDSS = 100 μA (max) (VDS = 30 V)

• Enhancement mode:  $V_{th} = 0.8 \text{ to } 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	30	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	30	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	2	Α	
	Pulse (Note 1)	I <sub>DP</sub>	6	Α	
Drain power dissipation	١	$P_{D}$	0.5	W	
Drain power dissipation (Note 2)		$P_{D}$	1.5	W	
Single pulse avalanche energy (Note 3)		E <sub>AS</sub>	56	mJ	
Avalanche current		I <sub>AR</sub>	2	Α	
Repetitive avalanche e	nergy (Note 4)	E <sub>AR</sub>	0.05	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55 to 150	°C	



Weight: 0.05 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	250	°C/W	

Note 1: Ensure that the channel temperature does not exceed 150°C.

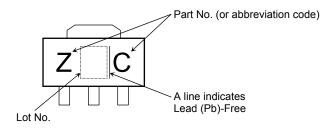
Note 2: Mounted on a ceramic substrate (25.4 mm × 25.4 mm × 0.8 mm)

Note 3:  $V_{DD}$  = 25 V,  $T_{ch}$  = 25°C (initial), L = 10 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 2 A

Note 4: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

### Marking



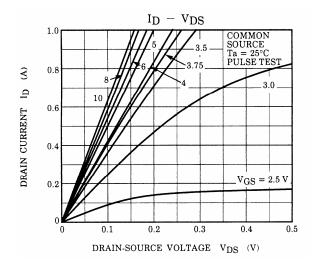
## **Electrical Characteristics (Ta = 25°C)**

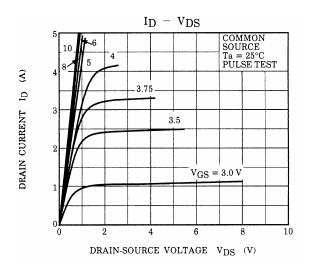
Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off current		I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	_	_	100	μА
Drain-source breakdown voltage		V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	30	_	_	V
Gate threshold v	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	8.0	_	2.0	V
Drain-source ON-resistance		_	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 1 A	_	0.18	0.25	Ω
		R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1 A	_	0.13	0.18	
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 A	1.2	2.5	_	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	140	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	30	_	
Output capacitance		C <sub>oss</sub>		_	80	_	
Switching time	Rise time	t <sub>r</sub>	VGS $\frac{10}{0}$ V $\frac{1}{0}$	_	10	_	- ns
	Turn-on time	ton		_	15	_	
	Fall time	t <sub>f</sub>		_	85	_	
	Turn-off time	t <sub>off</sub>		_	195	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$	_	5.8	_	nC
Gate-source charge		Q <sub>gs</sub>		_	4.3	_	
Gate-drain ("miller") Charge		Q <sub>gd</sub>		_	1.5		

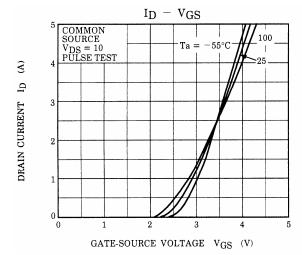
## Source-Drain Ratings and Characteristics (Ta = 25°C)

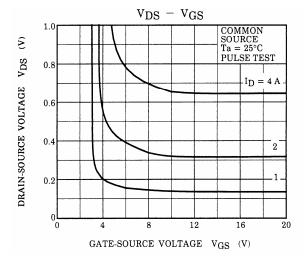
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	2	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	6	Α
Forward voltage (diode)	$V_{DSF}$	I <sub>DR</sub> = 2 A, V <sub>GS</sub> = 0 V	_	_	-1.5	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 2 A, V <sub>GS</sub> = 0 V, dI <sub>DR</sub> /dt = 50 A/μs	ı	50	_	ns
Reverse recovery charge	Q <sub>rr</sub>	1DR - 2 A, VGS - 0 V, αιDR/αι - 30 A/μs		20	_	nC

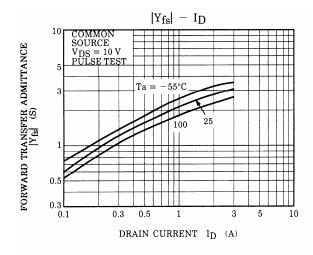
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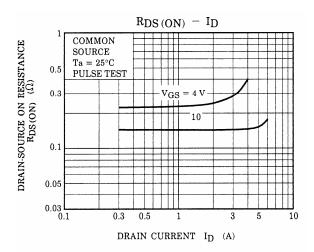




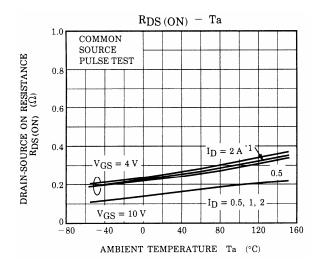


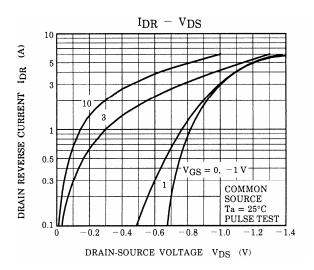


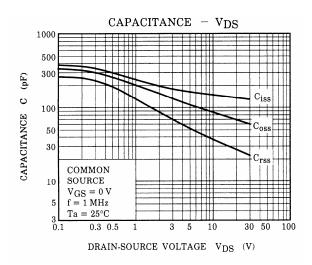


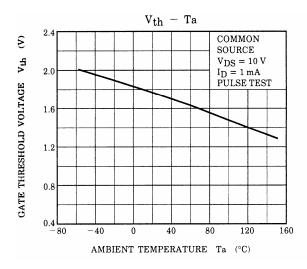


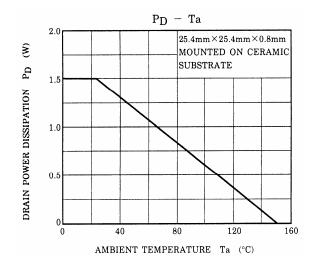
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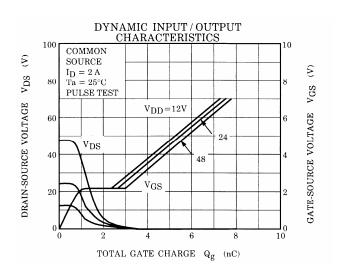




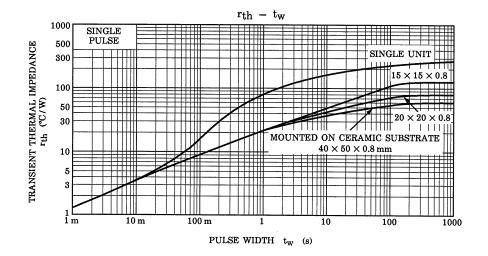


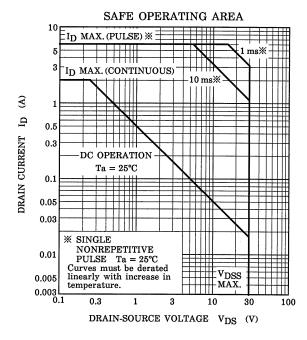


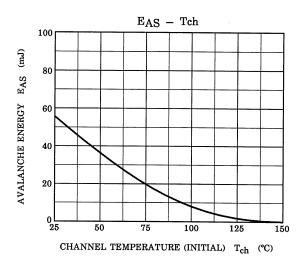


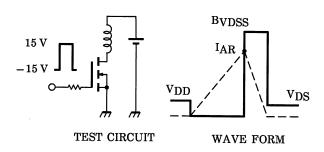


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 25~V,~L = 10~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right) \end{aligned}$$

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20070701-EN GENERAL

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